N-Channel 30-V (D-S), 175°C MOSFET

PRODUCT SUMMARY		
$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
30	0.0095 @ V_{GS} = 20 V	70
	0.014 @ V_{GS} = 4.5 V	58

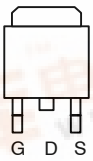
FEATURES

- TrenchFET® Power MOSFET
- Optimized for High- or Low-Side
- New Low Thermal Resistance Package
- 100% R_g Tested

APPLICATIONS

- DC/DC Converters
- Synchronous Rectifiers

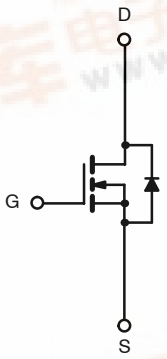
TO-263



DRAIN connected to TAB

Top View

Ordering Information: SUM70N03-09CP
SUM70N03-09CP-E3 (Lead Free)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C UNLESS OTHERWISE NOTED)				
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current (T_J = 175°C)	T_C = 25°C	I_D	70	A
	T_C = 125°C		40	
Pulsed Drain Current		I_{DM}	100	
Avalanche Current		I_{AR}	35	
Repetitive Avalanche Energy[a]	L = 0.1 mH	E_{AR}	61[b]	mJ
Maximum Power Dissipation[a]	T_C = 25°C	P_D	93	W
	T_A = 25°C[c]		3.75	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	−55 to 175	°C

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Limit	Unit
Junction-to-Ambient	PCB Mount[c]	R_{thJA}	40	°C/W
Junction-to-Case		R_{thJC}	1.6	

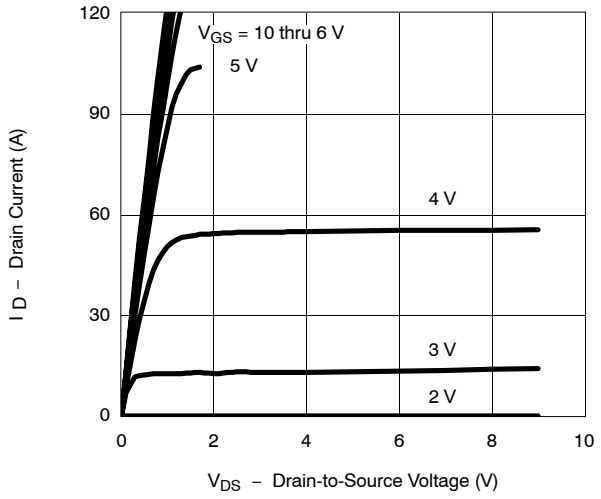
Notes:
a. Duty cycle ≤ 1%.
b. See SOA curve for voltage derating.
c. When mounted on 1" square PCB (FR-4 material).

SPECIFICATIONS (T_J = 25°C UNLESS OTHERWISE NOTED)						
Parameter	**Symbol**	**Test Condition**	**Min**	**Typ[a]**	**Max**	**Unit**
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 250 μA	30			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 μA	1.0		3.0	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 30 V, V_{GS} = 0 V			1	μA
		V_{DS} = 30 V, V_{GS} = 0 V, T_J = 125°C			250	
On-State Drain Current[b]	$I_{D(on)}$	V_{DS} = 5 V, V_{GS} = 10 V	100			A
Drain-Source On-State Resistance[b]	$r_{DS(on)}$	V_{GS} = 10 V, I_D = 20 A		0.0076	0.0095	Ω
		V_{GS} = 10 V, I_D = 20 A, T_J = 175°C			0.015	
		V_{GS} = 4.5 V, I_D = 20 A		0.0115	0.014	
Forward Transconductance[b]	g_{fs}	V_{DS} = 15 V, I_D = 20 A	20			S
Dynamic[a]						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		2200		pF
Output Capacitance	C_{oss}			410		
Reverse Transfer Capacitance	C_{rss}			180		
Gate Resistance	R_g		0.5	1.5	2.1	Ω
Total Gate Charge[c]	Q_g	V_{DS} = 15 V, V_{GS} = 10 V, I_D = 50 A		31	45	nC
Gate-Source Charge[c]	Q_{gs}			7.5		
Gate-Drain Charge[c]	Q_{gd}			5.0		
Turn-On Delay Time[c]	$t_{d(on)}$	V_{DD} = 15 V, R_L = 0.3 Ω I_D ≅ 50 A, V_{GEN} = 10 V, R_g = 2.5 Ω		9	15	ns
Rise Time[c]	t_r			80	120	
Turn-Off Delay Time[c]	$t_{d(off)}$			22	35	
Fall Time[c]	t_f			8	12	
Source-Drain Diode Ratings and Characteristic (T_C = 25°C)						
Pulsed Current	I_{SM}				100	A
Diode Forward Voltage[b]	V_{SD}	I_F = 50 A, V_{GS} = 0 V		1.2	1.5	V
Source-Drain Reverse Recovery Time	t_{rr}	I_F = 50 A, di/dt = 100 A/μs		35	70	ns

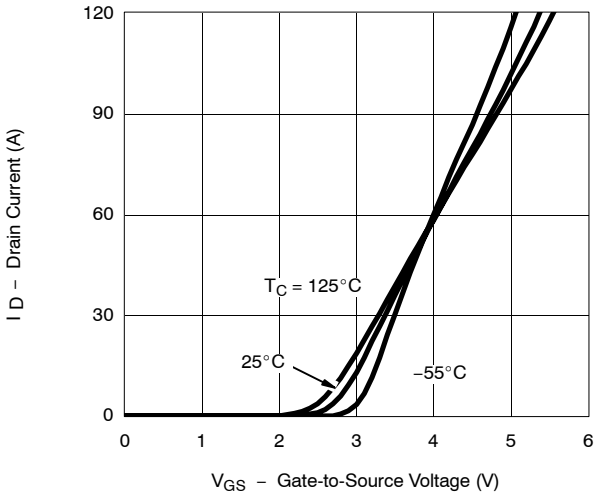
Notes
a. Guaranteed by design, not subject to production testing.
b. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
c. Independent of operating temperature.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

Output Characteristics

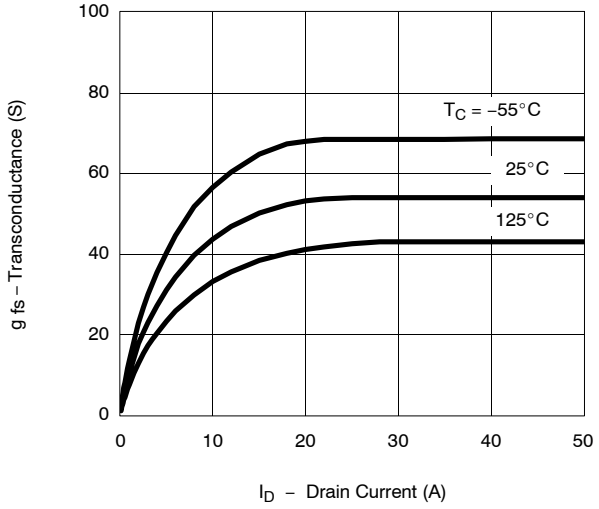


Transfer Characteristics

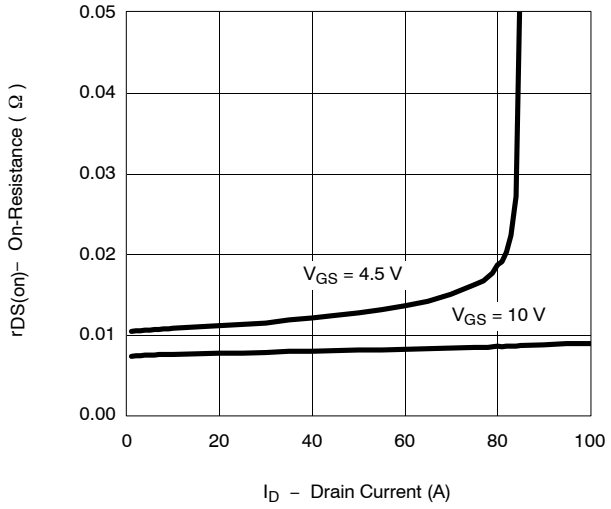


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

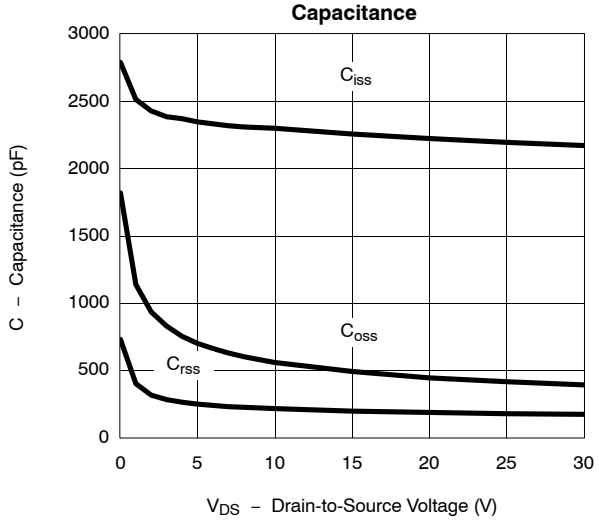
Transconductance



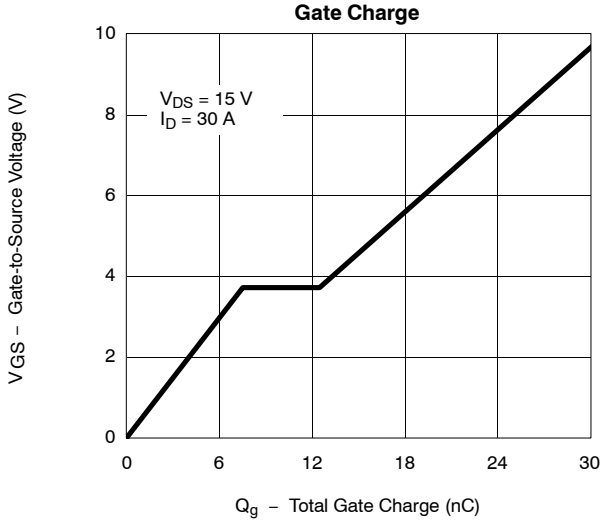
On-Resistance vs. Drain Current



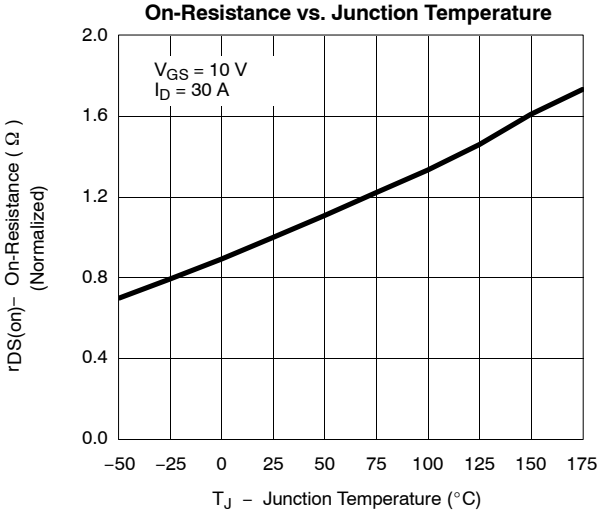
Capacitance



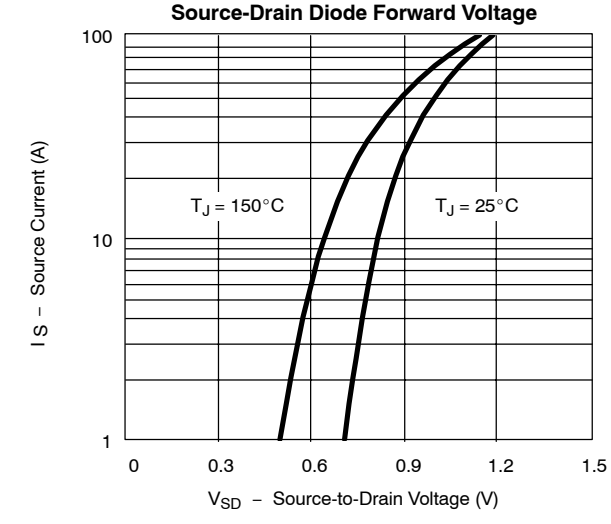
Gate Charge



On-Resistance vs. Junction Temperature

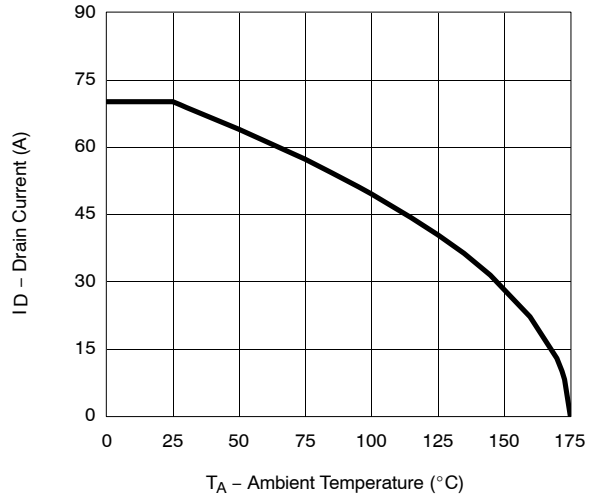


Source-Drain Diode Forward Voltage

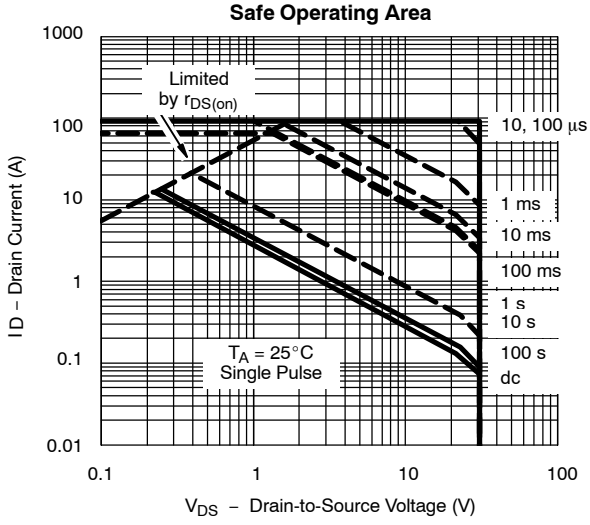


THERMAL RATINGS

Maximum Drain Current vs. Ambiemt Temperature



Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case